

FEATURES

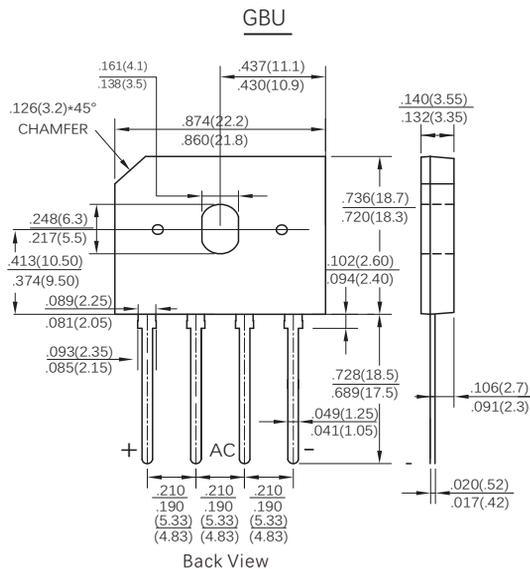
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated chip junction
- High current capability,Low forward voltage drop
- Soft recovery improves EMC performance
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Component in accordance to RoHS 2015/863/EU

MECHANICAL DATA

- Case: GBU molded plastic body
- Terminals: Plated leads solderable per MIL-STD-750,method 2026
- Mounting Position: Any

TYPICAL APPLICATIONS

Used in AC/DC bridge full wave rectification for SMPS, lighting ballaster, adapter, charger, home appliances, office equipment, and telecommunication applications.



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Rating at 25°C ambient temperature unless otherwise specified. Single phase ,half wave , resistive or inductive load. For capacitive load,derate current by 20%.)

| Parameters | Symbol | EGBU1006 | Units |
|--|--------------------|-----------------|------------------|
| Maximum Reverse Peak Reverse Voltage | V_{RRM} | 600 | Volts |
| Maximum RMS Voltage | V_{RMS} | 420 | Volts |
| Maximum DC Blocking Voltage | V_{DC} | 600 | Volts |
| Maximum Average Forward Rectified Current, (See Fig 2) | I_{FAV} | 10.0 | Amps |
| Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load | I_{FSM} | 175 | Amps |
| Rating for Fusing (t =8.3ms) | I^2t | 127 | A ² S |
| Maximum Instantaneous Forward Voltage at 5.0A DC | V_F | 1.70 | Volts |
| Maximum DC Reverse Current at rated DC blocking voltage | $T_A=25^{\circ}C$ | 5 | μA |
| | $T_A=125^{\circ}C$ | 100 | μA |
| Typical Junction Capacitance (Note 1) | C_j | 55 | pF |
| Typical thermal resistance (Note 2) | Junction-Ambient | $R_{\theta JA}$ | 25 |
| | Junction-Case | $R_{\theta JC}$ | 2.0 |
| Maximum reverse recovery time(Note3) | trr | 35 | ns |
| Operating junction and storage temperature range | T_j / T_{STG} | -55 to +150 | $^{\circ}C$ |

NOTE: 1.Measured at 1MHz and applied reverse voltage of 4.0 Volts.

2 Unit mounted on 50mm x 50mm x 1.6mm copper plate heatsink

3. Test conditions: $I_s=0.5A, I_R=1.0A, I_{RM}=0.25A$.

FIG.1-MAXIMUM FORWARD SURGE CURRENT

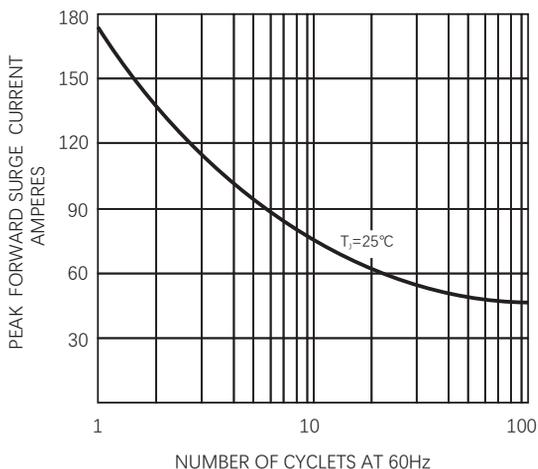


FIG.2 FORWARD CURRENT DERATING CURVE

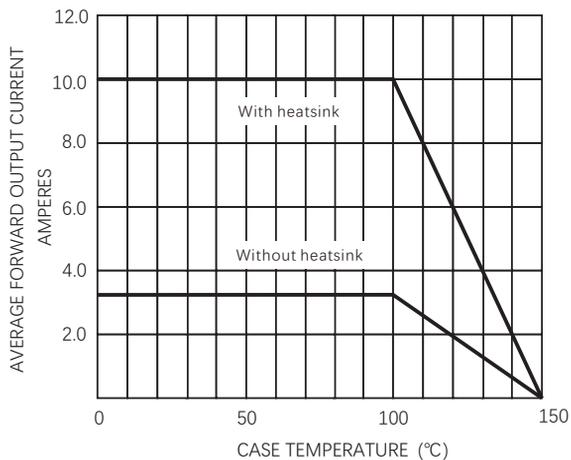


FIG. 3-TYPICAL FORWARD CHARACTERISTICS

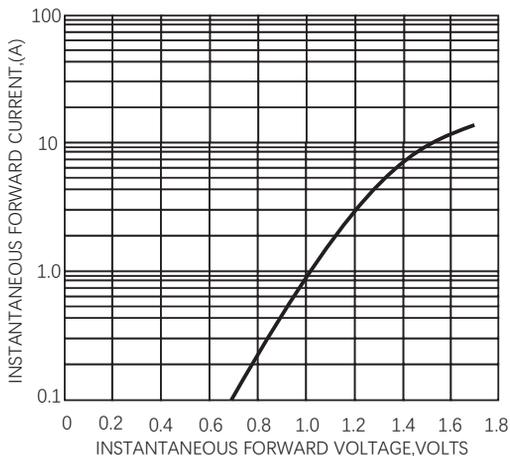
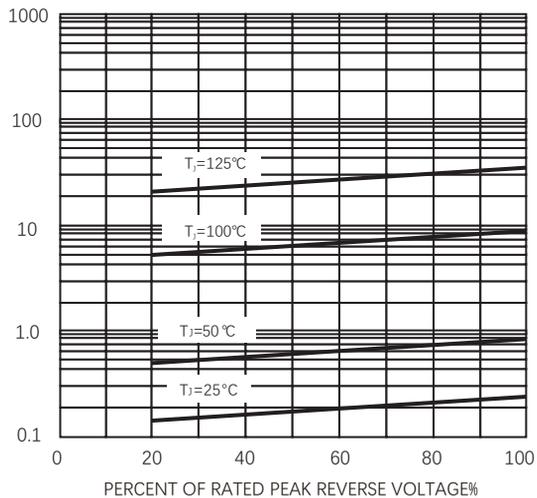


FIG.4 -TYPICAL REVERSE CHARACTERISTICS



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